



**RELTEK** LLC

adhesives, sealants & coatings for harsh environments

# **BONDIT™ B-755\***

## **Clear Coat, Sealant and Adhesive System**

### **Coating & Potting**

A unique fast set, low viscosity, ambient cure, water-white, scratch resistant UV resistant epoxy for clear-coatings of many surfaces, conformal coat of electronics, electrical component encapsulation and potting with excellent ambient cure properties.

### **High performance**

High temperature to 600 °F, excellent chemical resistance, high strength even with ambient cure. rugged semi-rigid system. The product is also available in the filled (thixotropic). Bonds to many substrates such as GRE circuit boards and FKM elastomer

### **Easy to use**

Two-part, primerless, ambient cure system with low HAZMAT impact for work environment. Available in handheld and pneumatic gun actuated cartridges, quarts, gallons and drums.

### **Harsh environments**

Marine,  
Civil Engineering,  
Downhole oil,  
Underwater,  
Electronic,  
Mining,  
Industrial,  
Automotive.

\*Experimental - properties not fully evaluated and system is subject to formulation revisions





## BONDIT™ B-755

### Description

**BONDIT™** B-755 is a unique low viscosity, two-part, high strength, 100% solids, room-temperature curing semi-rigid cyclo-aliphatic epoxy resin system with good scratch and impact resistance. Suitable for clear coat, conformal coating and electrical potting applications. The B-755 handles harsh environments easily and is effective against moisture, salt water, acids, alkalies, oils, fuels, solvents and detergents. B-755 produces very low extract products in soak tests and provides corrosion resistance.

BONDIT B-755 exhibits superior thermal resistance compared to most epoxy systems, particularly those offering ambient curing temperature. DMA testing demonstrate stability to 600°F. Excellent for fuel cell applications.

Apply B-755 by static mixer, brush or roller. B-755 is very easy to use with low HAZMAT impact as a 100% solids epoxy system—no solvents or VOC problems.

### Mixing, Curing, and Storage

Ambient cure (10 gram mix): 60 minute pot life; 90 minute gel time, 2 hours set time, 7 hours to 85% cure, dust free and may be roughly handled. Thin film ambient set time of 90 minutes and cure of 5 hours. Thermal cure at 135degF is approximately 10 minute. In 100gr quantity B-755 is exothermic which will shorten pot life. Mix part A with part B, 4:1 ratio by volume or 100/23.1 by weight. Thoroughly hand mix at least 4 minutes, or use static mixer. Degass is recommended. Optional surface prep will improve adhesion by abrading or grit blasting substrates with #100 AlOx followed by degrease and/or alcohol wipe.

The usable shelf life of unopened containers of **BONDIT™** B-755 resin is one year, and should be stored in cool, dry place. When not in use, containers should be kept tightly closed. Not UV sensitive; keep away from excess heat.

**BONDIT™** B-755 is available in side-by-side handheld and pneumatic actuated gun cartridges, quarts, gallons, pails and drums. Custom packaging, such as premixed and degassed frozen cartridges, is also available.

### Typical Properties

#### Property

Color	Clear water white
Viscosity	~500 cps

### Information

For further information, engineering support and sales service, contact **RELTEK** sales office.